

File No. 27(35)/2013-IPHW
Government of India
Ministry of Communications and Information Technology
Department of Electronics and Information Technology

Date: 23-12-2013

Subject: Amendment to Guidelines for Modified Special Incentive Package Scheme(MSIPS) to offset disability and attract investments in Electronics System Design and Manufacturing (ESDM) Industries.

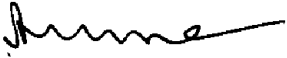
- Ref:**
1. MSIPS Policy Gazette Notification No. 175 dated 27-07-2012
 2. MSIPS Guidelines ref 27(3)/2012-IPHW dated 07-10-2012
 3. Amendment of MSIPS Guidelines ref 27(3)/2012-IPHW dated 23-05-2013

In partial modification of Modified Special Incentive Package Scheme(M-SIPS) Guidelines issued vide ref. 27(3)/2012-IPHW dated 07-10-2012 cited at reference-2 above, the following amendment is herein under made:

2. Para 6.3 of the aforesaid Guidelines shall be substituted with the following :

Para 6.3 *"A project proposed under the Scheme may include one or more electronic products in a single Initial Application. In case the same manufacturing set up/ production line is used for manufacturing more than one electronic products falling under verticals with different thresholds, the applicable threshold would be of the vertical which has the highest threshold. However, if the manufacturing set-up for the proposed products are significantly different, the applicable threshold would be sum of the thresholds required to manufacture each of the products separately."*

3. This issues with the approval of competent authority.


(Dr Ajay Kumar)
Joint Secretary
Tel : 24360160

To:

1. All Ministries/Departments of Govt. of India
2. Cabinet Secretariat
3. PMO
4. Planning Commission
5. Comptroller and Auditor General of India
6. All Members of Appraisal Committee (M-SIPS)
7. JS&FA, DeitY
8. OSD to Secretary, DeitY

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